

**Application No.: 10/757,388**

**AMENDMENT TO SPECIFICATION**

**Please amend the paragraph beginning on page 19, line 27 as follows:**

After that, as shown in Fig. 7B, the dicing groove 15 is formed by means of cutting from one side, on which the adhesive tape 14 is not stuck, to the other side, on which the adhesive tape 14 is stuck, with the dicing blade 16, so that the semiconductor device [[ca be]] can be separated.